WeEn
WeEn Semiconductors

WMSC008H12B2S

N-Channel Silicon Carbide MOSFET Module

Rev.02 - 24 September 2024 — Product data sheet

RoHS Halogen-Free Lead-Free

1. General description

WeEnPACK-B2 module with WeEn 1200V Gen2 SiC MOSFET and Solder pin type. Integrated with NTC temperature sensor.

2. Features and benefits

- Half bridge topology
- Solder pin configuration
- Low R_{DSon}-T_j coefficient
- Low Switching Losses
- Low Q_g and C_{rss}
- Mimimized circuit impedance
- Improved chip synchronization performance

3. Applications

- Power inverters
- AC-DC converters
- DC-DC converters
- Active power factor correctors
- Motor drives

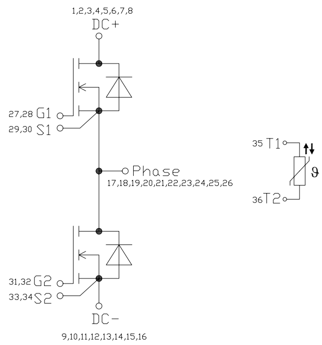
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Absolute maximum rating							
V_{DS}	drain-source voltage	T_j = 25 °C			1200		V
I_D	drain current	V_{GS} = 18 V; T_h = 25 °C			157		A
P_{tot}	total power dissipation	T_h = 25 °C			272		W
$T_{j.op}$	operating junction temperature				-40 to 150		°C
Symbol	**Parameter**	**Conditions**	**Notes**	**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
$R_{DS(on)}$	drain-source on-state resistance	V_{GS} = 15 V; I_D = 150 A; T_j = 25 °C		-	8.0	-	mΩ
		V_{GS} = 18 V; I_D = 150 A; T_j = 25 °C		-	6.7	13	mΩ
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	I_D = 150 A; V_{DS} = 800 V; V_{GS} = 0 V/18 V; T_j = 25 °C		-	536	-	nC
Q_{GD}	gate-drain charge			-	102	-	nC
Source-drain diode							
Q_r	recovered charge	I_{SD} = 150 A; V_{GS} = -4 V/18 V; V_R = 600 V; di/dt =2700 A/μs;		-	928	-	nC

5. Pinning information

Table 2. Pinning information

Simplified outline	Circuit diagram
 * Please refer to the package outline description for actual pin order.	

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WMSC008H12B2S	WeEnPACK-B2	WMSC008H12B2S6T	Tray	12	WeEnPACK-B2PHB-A	31-Jan-2024

7. Marking

Table 4. Marking codes

Type number	Marking codes
WMSC008H12B2S	WMSC008H12B2S

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
T_{stg}	storage temperature			-40 to 125	°C
$T_{j.op}$	operating junction temperature			-40 to 150	°C
$T_{j.max}$	maximum junction temperature	Intermittent condition with shortened lifetime		-40 to 175	°C
V_{ISOL}	RMS isolation voltage	T_j = 25 °C; all terminals shorted; f = 50 Hz; t = 1 s		3500	V
MOSFET					
V_{DS}	drain-source voltage	T_j = 25 °C		1200	V
$V_{GS,max}$	gate-source voltage	Absolute maximum values		-12 to 24	V
$V_{GS,op}$	gate-source voltage	Recommended operational values		-4 to 18	V
P_{tot}	total power dissipation	T_h = 25 °C		272	W
I_D	drain current	V_{GS} = 18 V; T_h = 25 °C		157	A
		V_{GS} = 18 V; T_h = 100 °C		99	A
I_{DM}	peak drain current	pulsed; tp ≤ 10 us; T_h = 25 °C		350	A
E_{as}	single pulse drain−to-source avalanche	I_{AS} = 24 A; L = 1 mH; V_{DD} = 100 V; $T_{j(init)}$ = 25 °C; each die		288	mJ
Body Diode					
I_{SD}	DC body diode forward current	T_h = 25 °C; V_{GS} = -4 V		65	A
$I_{SD,pulse}$	Pulse body diode current	verified by design, tp limited by T_{jmax}		350	A

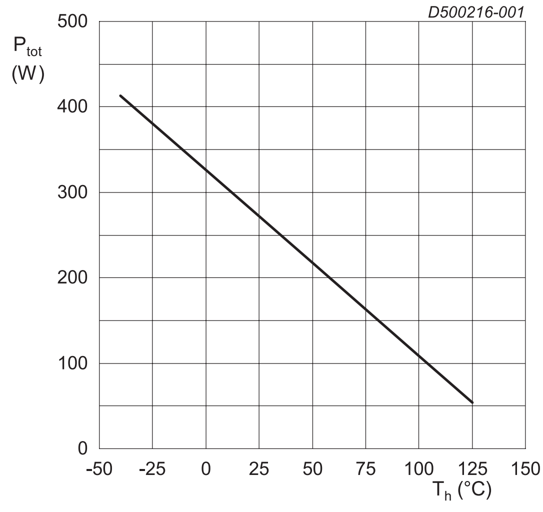


Fig. 1. Power dissipation as a function of heatsink temperature; maximum values

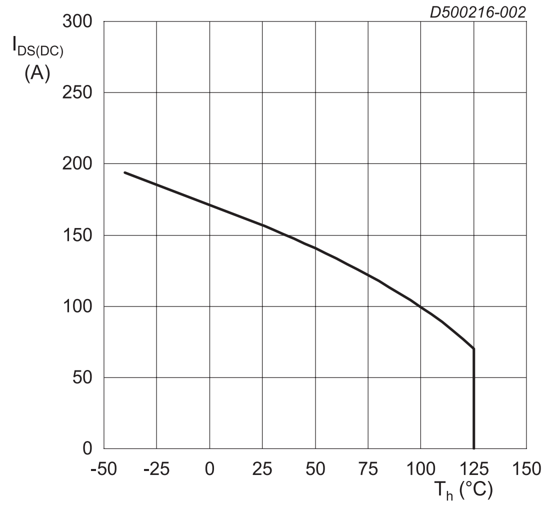


Fig. 2. Continuous Drain Current as a function of heatsink temperature

9. Thermal & Mechanical characteristics

Table 6. Thermal & Mechanical characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	per MOSFET		-	0.16	-	K/W
$R_{th(j-h)}$	thermal resistance from junction to heatsink	per MOSFET, λ_{grease} = 3 W/(m·K), $thick_{grease}$ = 50 um		-	0.46	-	K/W
Internal Isolation		basic insulation (class 1, IEC 61140)			Al_2O_3		
d_{Creep}	Creepage distance	terminal to heatsink		-	11.5	-	mm
		terminal to terminal		-	6.3	-	mm
d_{Clear}	Clearance	terminal to heatsink		-	10	-	mm
		terminal to terminal		-	5	-	mm
CTI	Comperative tracking index				>200		
F	Mounting force per clamp			40	-	80	N
G	Approximate Weight			-	36	-	g

Note: Module is ESD sensitive. Handling precautions are recommended.

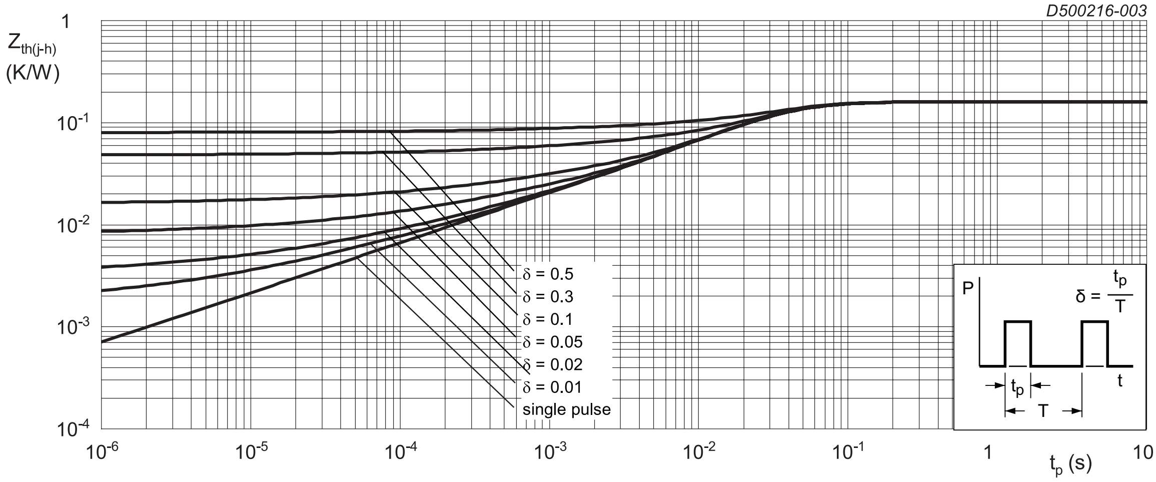


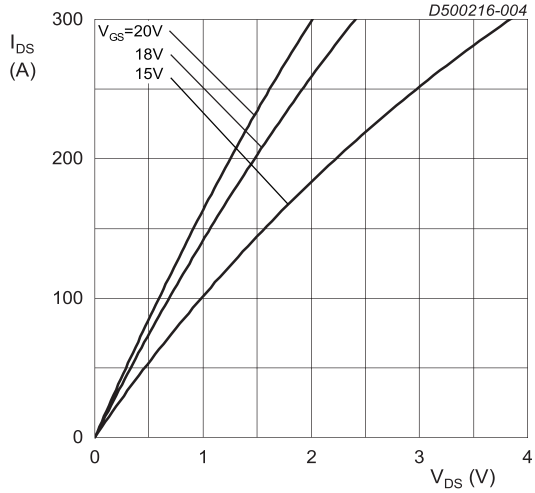
Fig. 3. Transient thermal impedance from junction to heatsink as a function of pulse duration

10. Characteristics

Table 7. Characteristics

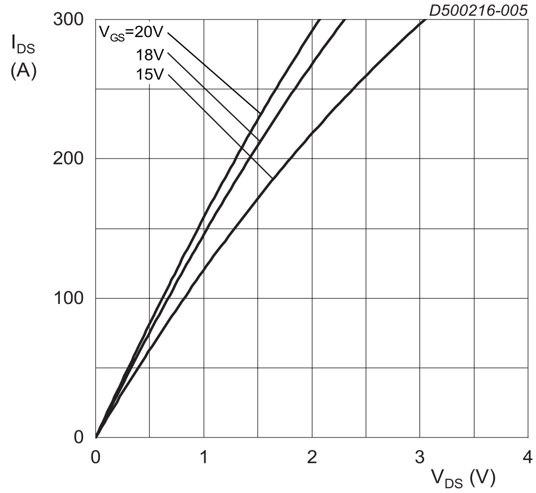
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
MOSFET							
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 400 µA; V_{GS} = 0 V; T_j = 25 °C		1200	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 48 mA; V_{DS} = 10 V; T_j = 25 °C		1.9	2.5	3.5	V
		I_D = 48 mA; V_{DS} = 10 V; T_j = 175 °C		-	1.9	-	V
I_{DSS}	drain leakage current	V_{DS} = 1200 V; V_{GS} = 0 V; T_j = 25 °C		-	1	400	µA
I_{GSS}	gate leakage current (absolute value)	V_{GS} = 24 V; V_{DS} = 0 V; T_j = 25 °C		-	40	400	nA
		V_{GS} = -12 V; V_{DS} = 0 V; T_j = 25 °C		-	40	400	nA
$R_{DS(on)}$	drain-source on-state resistance	V_{GS} = 15 V; I_D = 150 A; T_j = 25 °C		-	8.0	-	mΩ
		V_{GS} = 18 V; I_D = 150 A; T_j = 25 °C		-	6.7	13	mΩ
		V_{GS} = 18 V; I_D = 150 A; T_j = 125 °C		-	10	-	mΩ
		V_{GS} = 18 V; I_D = 150 A; T_j = 150 °C		-	11	-	mΩ
		V_{GS} = 18 V; I_D = 150 A; T_j = 175 °C		-	11.6	-	mΩ
R_G	gate resistance	f = 1 MHz; T_j = 25 °C; each die with 4.7Ω $R_{G,ext}$ in series		-	1.27	-	Ω
g_{fs}	transconductance	V_{DS} = 20 V; I_D = 150 A; T_j = 25 °C		-	55	-	S
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	I_D = 150 A; V_{DS} = 800 V; V_{GS} = 0 V/18 V; T_j = 25 °C		-	536	-	nC
Q_{GS}	gate-source charge			-	172	-	nC
Q_{GD}	gate-drain charge			-	102	-	nC
C_{iss}	input capacitance	V_{DS} = 1000 V; V_{GS} = 0 V; f = 1 MHz; T_j = 25 °C		-	13	-	nF
C_{oss}	output capacitance			-	575	-	pF
C_{rss}	reverse transfer capacitance			-	60	-	pF
E_{oss}	Coss stored energy			-	290	-	µJ
$t_{d(on)}$	turn-on delay time	V_{DS} = 800 V; V_{GS} = -4 V/18 V; $R_{G(off)}$ = 2.4 Ω; $R_{G(on)}$ = 2.4 Ω; I_D = 150 A; L = 100 µH; T_j = 25 °C		-	82	-	ns
t_r	rise time			-	70	-	ns
$t_{d(off)}$	turn-off delay time			-	210	-	ns
t_f	fall time			-	75	-	ns
E_{on}	turn-on energy			-	5.4	-	mJ
E_{off}	turn-off energy			-	2.3	-	mJ

Body diode							
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_{SD}	source-drain voltage	V_{GS} = -4 V; I_{SD} = 150 A; T_j = 25 °C		-	5.8	-	V
		V_{GS} = -4 V; I_{SD} = 150 A; T_j = 150 °C		-	5.2	-	V
Dynamic characteristics							
I_{rrm}	reverse recovery current	I_{SD} = 150 A; V_{GS} = -4 V/18 V; V_R = 600 V; di/dt = 2700 A/µs; $R_{G(ext)}$ = 5.1 Ω; T_j = 25 °C		-	62	-	A
t_{rr}	reverse recovery time			-	27	-	ns
Q_r	recovered charge			-	928	-	nC
E_{rec}	reverse recovery energy			-	61	-	µJ
NTC thermistor							
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
R_{25}	Rated resistance	T_{NTC} = 25 °C		-	5000	-	Ω
R_{100}		T_{NTC} = 100 °C			493±5%		Ω
$B_{25/50}$	B-value	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298.15K))]$			3380		K
	Maximum operating temperature			-	200	-	°C
	Dissipation costant			-	2	-	mW/K
	Thermal time constant			-	≤10	-	s



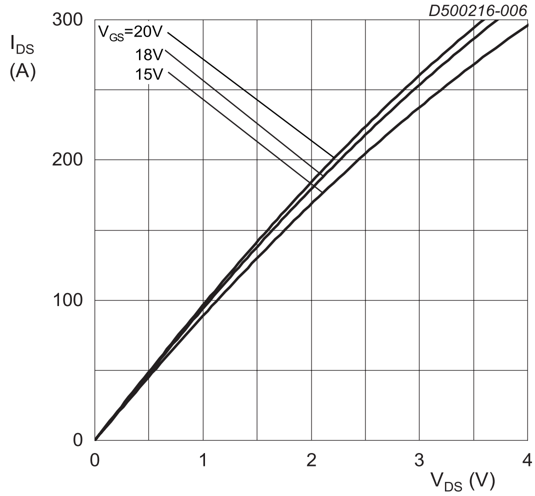
T_j = -40 °C; t_p < 200 µs

Fig. 4. Output characteristics; drain current as a function of drain-source voltage; typical values



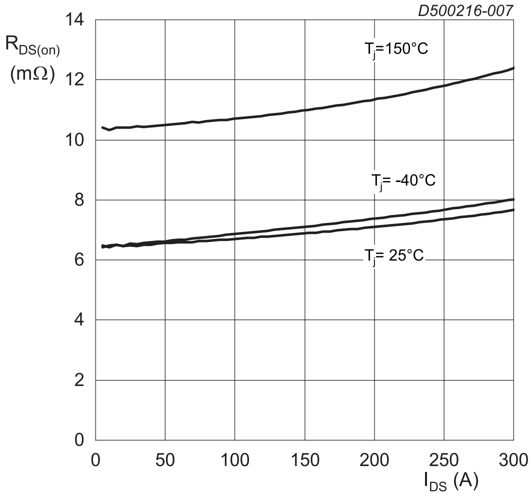
T_j = 25 °C; t_p < 200 µs

Fig. 5. Output characteristics; drain current as a function of drain-source voltage; typical values



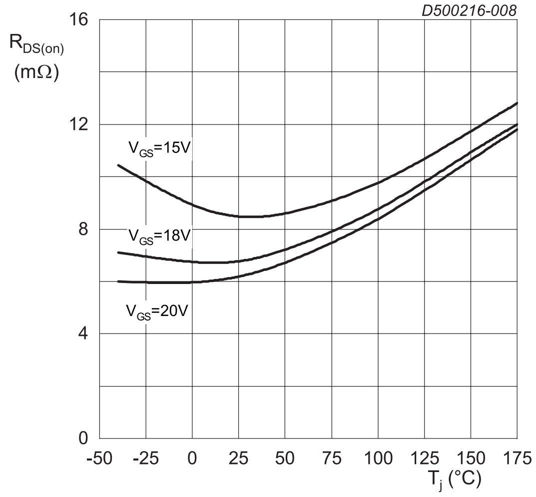
T_j = 150 °C; t_p < 200 µs

Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values



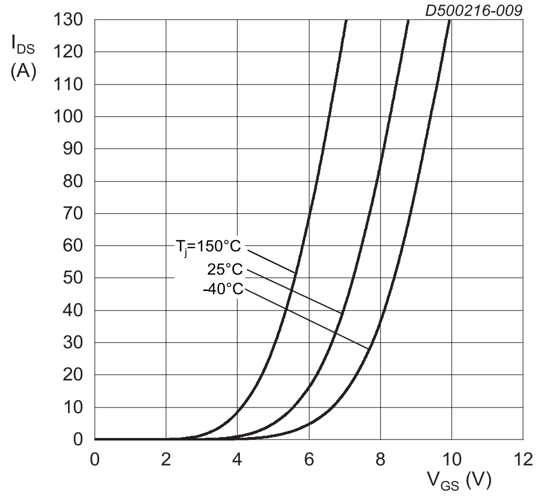
V_{GS} = 18 V; t_p < 200 µs

Fig. 7. Drain-source on-state resistance as a function of drain current; typical values



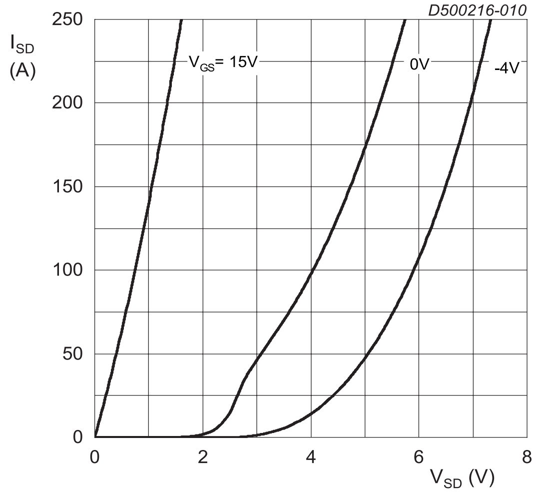
I_{DS} = 150 A; t_p < 200 µs

Fig. 8. Drain-source on-state resistance as a function of junction temperature



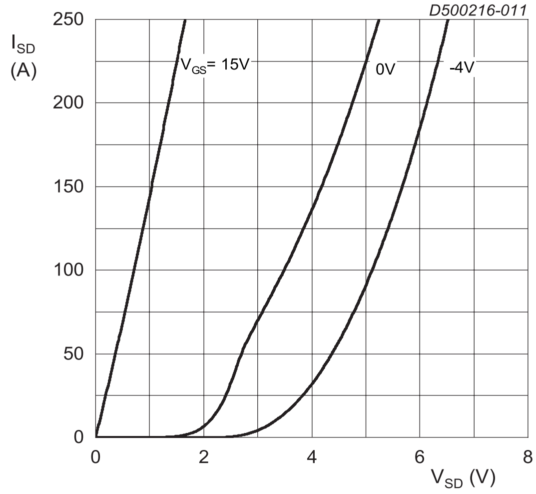
V_{DS} = 20 V; t_p < 200 µs

Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values



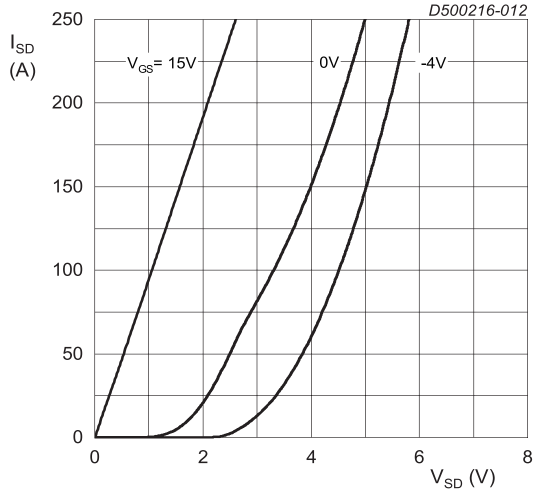
T_j = -40 °C; t_p < 200 µs

Fig. 10. Body diode forward characteristics; typical values



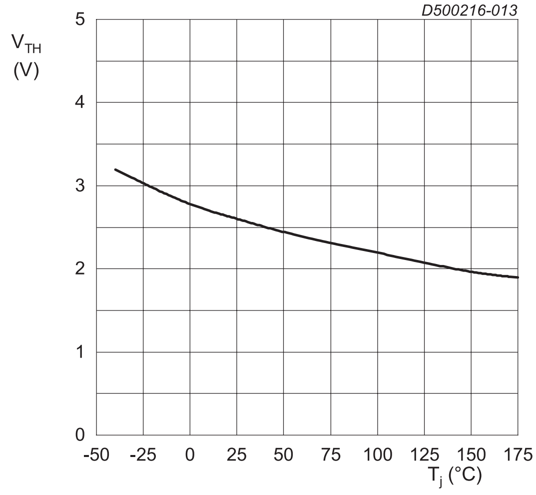
T_j = 25 °C; t_p < 200 µs

Fig. 11. Body diode forward characteristics; typical values



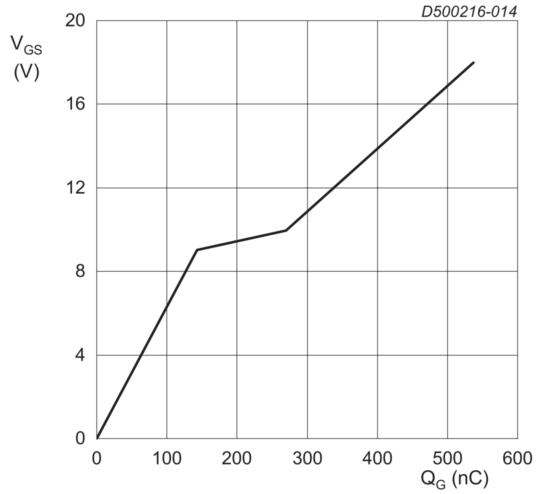
T_j = 150 °C; t_p < 200 µs

Fig. 12. Body diode forward characteristics; typical values



V_{DS} = 10 V; I_{DS} = 48 mA

Fig. 13. Threshold voltage as a function of junction temperature



I_{DS} = 150 A; I_{GS} = 0.1 mA; V_{DS} = 800 V; T_j = 25 °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

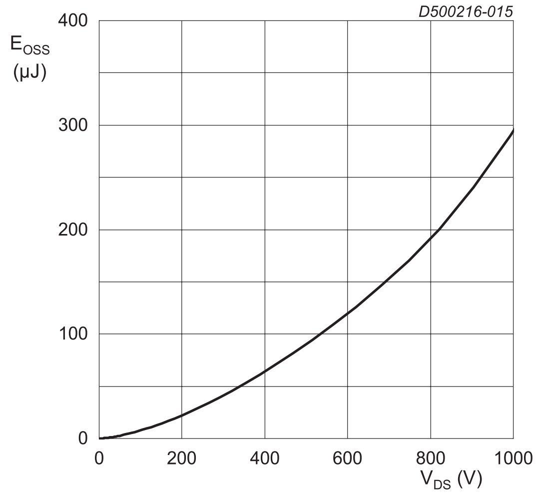
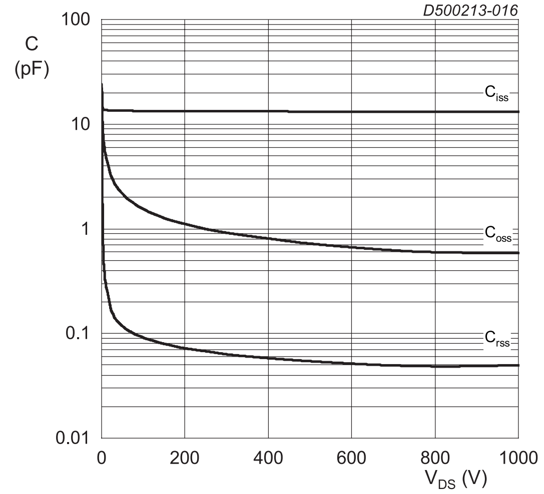
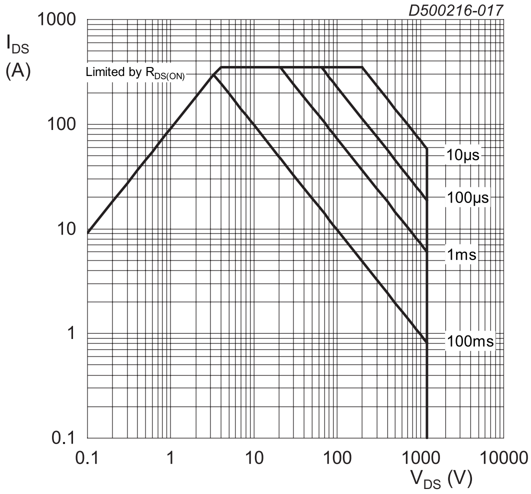


Fig. 15. Output capacitor stored energy as a function of drain-source voltage



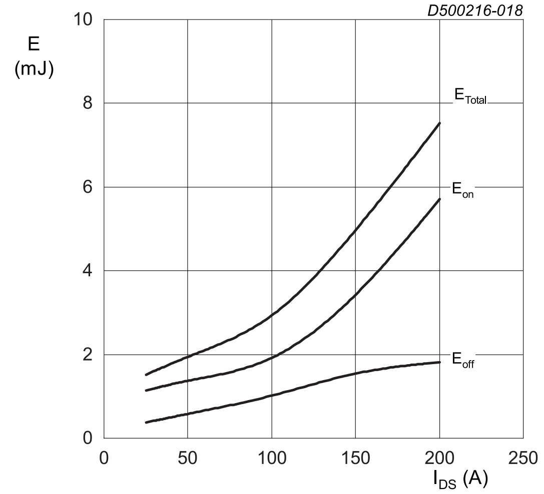
V_{DS} = 0 - 1000 V
T_j = 25 °C; V_{AC} = 25 mV; f = 1 MHz

Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



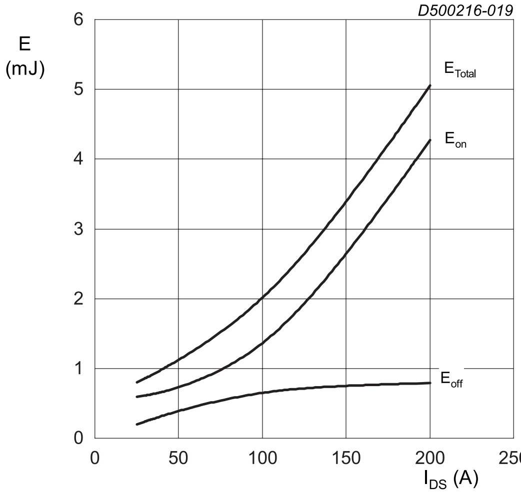
T_j = 25 °C; D = 0
Parameter: t_p

Fig. 17. Forward bias safe operating area



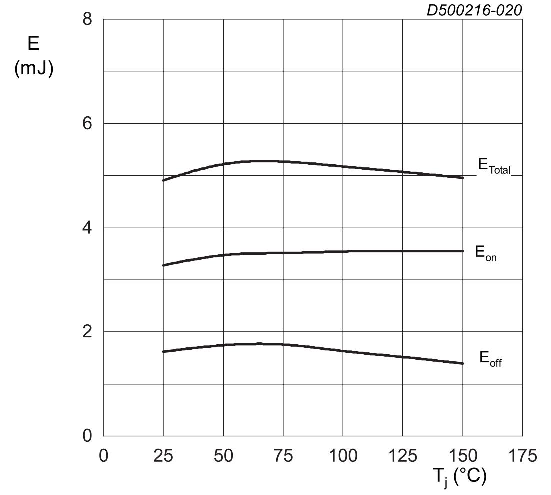
T_j = 25 °C; V_{DD} = 800 V; $R_{G(off)}$ = 2.4 Ω; $R_{G(on)}$ = 2.4 Ω;
V_{GS} = -4 V/18 V; L = 100 µH

Fig. 18. Clamped Inductive Switching Energy as a function of drain current



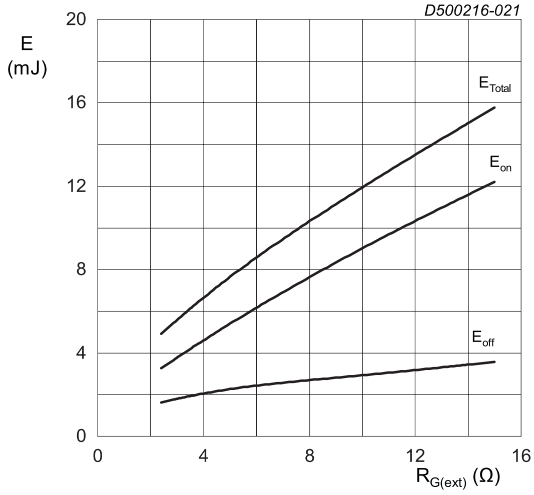
T_j = 25 °C; V_{DD} = 600 V; $R_{G(off)}$ = 2.4 Ω; $R_{G(on)}$ = 2.4 Ω;
V_{GS} = -4 V/18 V; L = 100 µH

Fig. 19. Clamped Inductive Switching Energy as a function of drain current



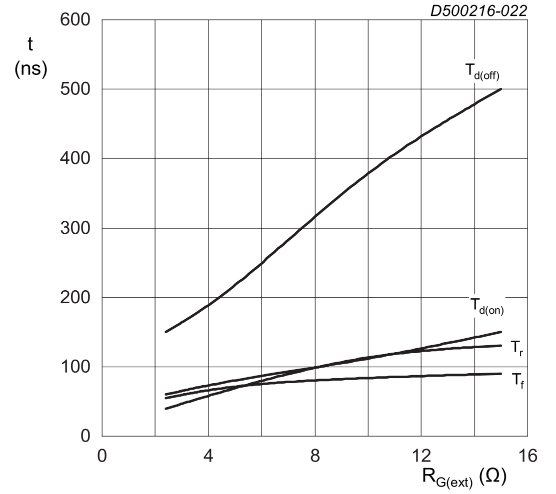
I_{DS} = 150 A; V_{DD} = 800 V; $R_{G(off)}$ = 2.4 Ω; $R_{G(on)}$ = 2.4 Ω; V_{GS} = -4 V/18 V; L = 100 µH

Fig. 20. Clamped Inductive Switching Energy as a function of junction temperature



T_j = 25 °C; V_{DD} = 800 V; I_{DS} = 150 A; V_{GS} = -4 V/18 V; L = 100 µH

Fig. 21. Clamped Inductive Switching Energy as a function of external gate resistance



T_j = 25 °C; V_{DD} = 800 V; I_{DS} = 150 A; V_{GS} = -4 V/18 V; L = 100 µH

Fig. 22. Switching time as a function of external gate resistance

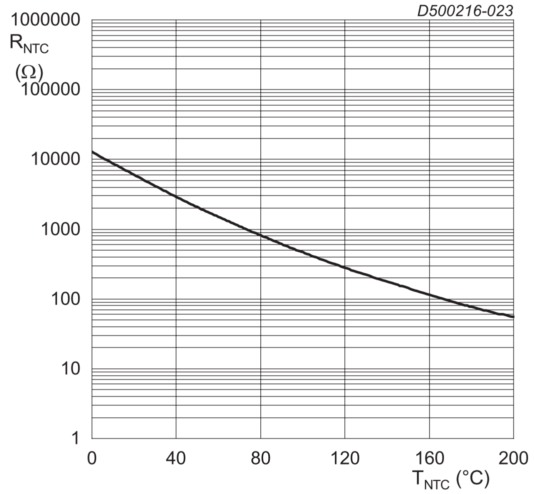
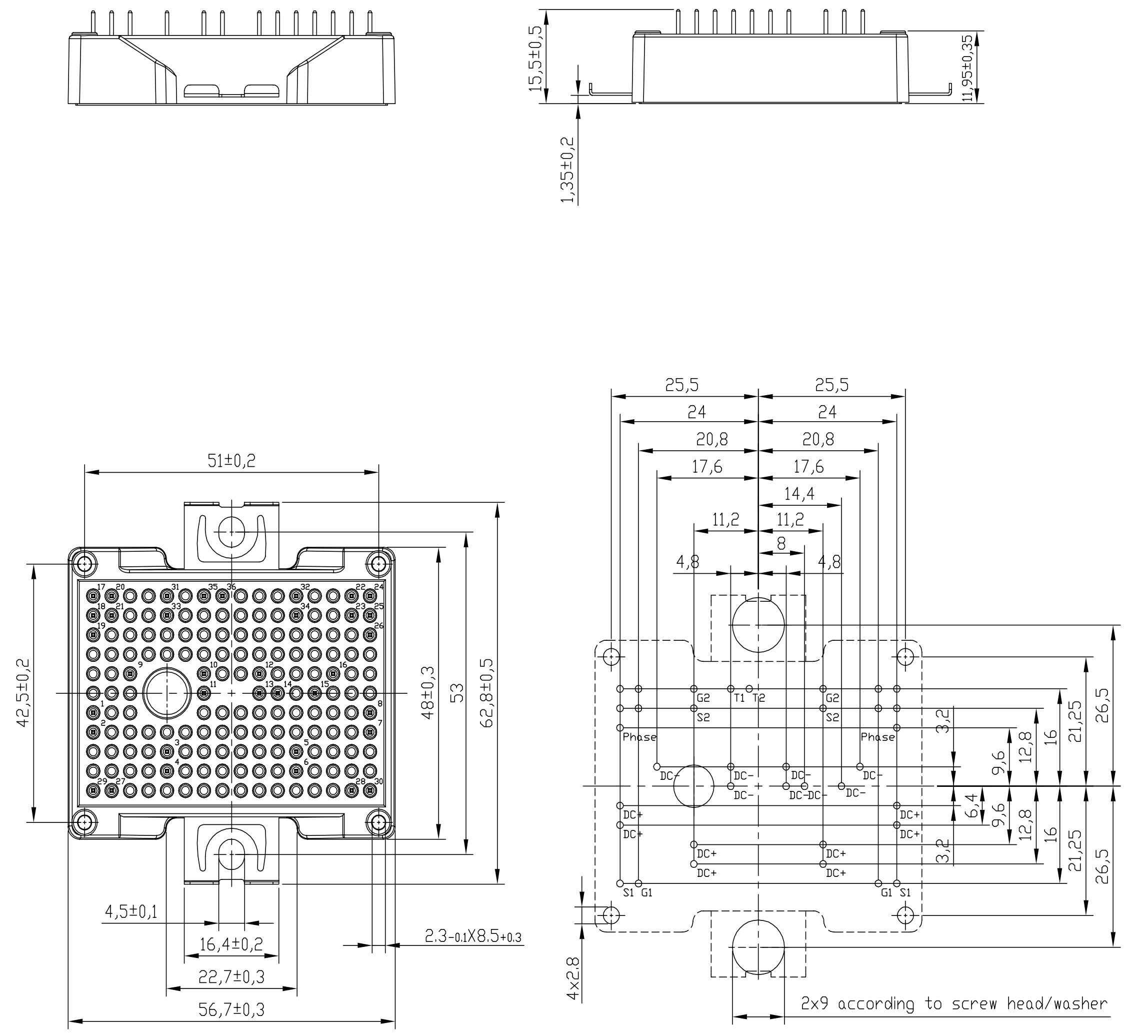


Fig. 23. NTC thermistor resistance as a function of NTC temperature

11. Package outline

Package Outline

Dimensions in mm



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

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For more information, please visit: http://www.ween-semi.com
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